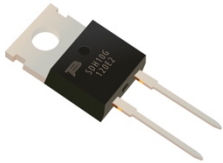


# MATERIAL DECLARATION SHEET



Material Number	BSDH10G120E2 TO220-2			
Product Line	Semiconductor			
Compliance Date	2023-3-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	2.49	Silicon Carbide (SiC)	409-21-2	100	0.12	0.12
2	Die Attach	Silver	0.06	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.00	0.05
			1.05	Silver (Ag)	7440-22-4	95	0.05	
3	Lead Frame	Copper alloy	0.43	Phosphorous (P)	7723-14-0	0.03	0.02	70.41
			1.42	Iron (Fe)	7439-89-6	0.10	0.07	
			1415.16	Copper (Cu)	7440-50-8	99.87	70.32	
4	Mold Compound	Resin	37.38	Phenol Formaldehyde resin (generic)	9003-35-4	6.5	1.86	28.58
			92	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	16	4.57	
			408.25	Silica fused	60676-86-0	71	20.29	
			37.38	Metal hydroxide	Trade Secret	6.5	1.86	
5	Post-plating	Lead alloy	15	Tin (Sn)	7440-31-5	100	0.75	0.75
6	Wire	Pure metal	1.68	Aluminium (Al)	7429-90-5	100	0.08	0.08
Total weight			2012.3 mg					

This Document was updated on: 2023/3/22  
 (EU) RoHS Directive 2011/65/EU ANNEX Application of lead which is exempt from the requirements